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Texas Instruments High Rel Products Reliability Report

Device Type/Device Family: TPS76901SHKJ/HKQ
 Package Type: 8 CFP/CSOIC
 Wafer Fabrication Facility: Dallas Linear
 Assembly/Test Facility: Millennium Microtech
 Compiled: 9/12

Biased Life Test

Test Method: JESD22-A108
 Test Condition: 210°C / 1000 hours
 Sample Size: 45
 Rejects: 0
 Activation Energy (eV): .5
 Equivalent Device Hours: 45000
 Failure Rate (FIT)*: 20491

* 60% confidence level of random failure rate during nominal 1000 hour life based on test sample size. This not based on wear out failure mechanisms which will begin to affect past the 1000 hr test limit.

Group B Tests (Weekly by Package Family)			
Description	Condition	Referenced Method	Sample Size/Rejects
B1 Resistance to Solvents		Mil Std 883 Method 2015	3/0
B2 Bond strength	Test condition F (FC)	Mil Std 883 Method 2011/2019/2027	22/0-3/0
B3 Solderability	Soldering temperature of 245C±5	Mil Std 883 Method 2003	22/0
Group C Test (Per 3 Month Period by Family)			
Description	Condition	Referenced Method	Sample Size/Rejects
C1 Steady-state life test	125C/1000Hrs 4.6V	Mil Std 883 Method 1005	45/0
End point electrical			45/0

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Group D Tests (Annually by Package Family)			
Description	Condition	Referenced Method	Sample Size/Rejects
D1 Physical Dimensions		Mil Std 883 Method 2016	15/0 *
D2 Lead Integrity		Mil Std 883 Method 2004 & 2028	45/0 *
Seal(Fine and Gross)		Mil Std 883 Method 1014	45/0 *
D3 Thermal Shock	-65°C to +150°C 15 cycles	Mil Std 883 Method 1011	
Temperature Cycle	-65°C to +150°C 100 cycles	Mil Std 883 Method 1010	*
Moisture Resistance		Mil Std 883 Method 1004	
Seal(Fine and Gross)		Mil Std 883 Method 1014	*
Visual examination		Mil Std 883 Method 1004 & 1010	
End point electrical D4			15/0 *
Mechanical Shock		Mil Std 883 Method 2002	
Variable Freq Vibration		Mil Std 883 Method 2007	*
Constant acceleration		Mil Std 883 Method 2001	
Seal		Mil Std 883 Method 1014	*
Visual Examination		Mil Std 883 Method 2009	
End point electrical D5			15/0 *
Salt Atmosphere		Mil Std 883 Method 1009	
Seal		Mil Std 883 Method 1014	*
Visual Examination		Mil Std 883 Method 1009	15/0
D6 Internal Water Vapor		Mil Std 883 Method 1018	3/0
D7 Adhesion of Lead Finish		Mil Std 883 Method 2025	15/0

Supplemental Device Characteristics

Die Revision:	A	Assembly Site:	ALP
Master Die:	BLBDPX76901AW	Package Type:	HKJ/HKQ
Wafer Fab:	DFAB	Pin Count:	8
Fab Technology:	LBC	Mold Compound:	Ceramic
Fab Process:	LBC3S	Mount Compound:	JM7000
Process Code:	N/A	Bond:	1.25 AL
Passivation:	Nitride	Lead Composition:	Kovar
Lead Finish:	Au		

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